**Material Set Change:**

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| Package Material Set | | Carsem | ASE Chungli |
| 8L and 10L MSOP | Die Attach | Ablestik 84-1 LMISR4  Hysol QMI519 | Hitachi EN4900 |
| Mold Compound | Sumitomo 6600H  Hitachi CEL8240HF10LX  Sumitomo G600 | Sumitomo G700 |
| Wire | Tanaka GLD 4N Gold 1mil  Tanaka M3 4N Gold 1mil  Tanaka M3 Gold 1mil | Heraues Relmax 2N Au 1mil  Tanaka GPG – 2N AU 0.8mil |